

Serial. No. 09/836,426  
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Examiner: Shantese L. McDonald

In the Specification

Please replace the first full paragraph on page 8 with the following replacement paragraph.

Lower polishing module 502 is generally configured to cause the polishing surface to move. By way of example, lower module 502 may be configured to cause the polishing surface to rotate, translate, orbit, or any combination thereof. In accordance with one embodiment of the invention, lower module 502 is configured such that platen 504 orbits with an orbital radius of about 0.25 to 1 inch, about an axis 522 at about 500 to about 200 2000, and preferably about 1000 revolutions per minute, while simultaneously causing the platen 504 to dither or partially rotate, such that the relative velocity between the wafer surface and the polishing surface is about 0.5 to about 3.2 meters/second. An orbital polishing module is described in greater detail in United States Patent No. 5,554,064, issued to Breivogel et al., the content of which is incorporated herein by reference.